

Appl. No. 09/753,188  
Amdt. dated January 23, 2004  
Reply to Office Action of October 23, 2003

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

Claims 1-38 (Canceled)

Claim 39 (currently amended): Method of mounting an interconnection element to a ~~terminal of an electronic component~~ substrate, comprising:

attaching an elongate element of a first material to a ~~terminal of an electronic component~~ substrate;

shaping the elongate element with a shaping tool; and

overcoating the elongate element with a second material which has a higher yield strength than the first material, in an amount sufficient for imparting a desired resiliency to the interconnection element, whereby the interconnection element after the overcoating step is substantially stiffer than the elongate element prior to the overcoating step.

Claim 40 (currently amended): Method, according to ~~claim 39~~ claim 54, further comprising:

while overcoating the elongate element, overcoating at least a portion of an exposed surface of the terminal with the second material.

Claims 41-53 (Canceled)

Claim 54 (new): The method of claim 39, wherein the substrate is an electronic component, and the elongate element is attached to a terminal of the electronic component.

Claim 55 (new): The method of claim 39, wherein the substrate comprises a lithographically defined part.

Claim 56 (new): The method of claim 55, wherein the elongate element is attached to the lithographically defined part.